Ι.	Hits	Jean d. Text	DB	Time stamp
Humbet 1	ŕ	traces and wads	USPAT; US-PGPUB; EPC; JPO; DEFWENT; IPM TDB	
	2000	·laces and pads	US PGPUB; EF.; JPC; DEEWENT; IBM TDB	
	* 4.53	otiaces and padso and solder	US-PGPUB; EFO; JPO; DERWENT; IBM_TDB	2003/03/17
-1	¥200.	substrate board carrier poblob pbs and traces and pads and solder	USEAT; USEPGPUB; EE:; JPC; DEPWENT; IBM_TDB	0003, 33, 17 10:25
τ	23/5	substrate board carrier publish pho and straces and pads) and solders and and sinautive active)	USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/03/17
r	210	((substrate board carrier pcb cb pb) and ((traces and pads) and solder); and ((nactive and active)	USPAT; US-PGPUB; EPO; JPO; DEPWENT; IBM TDB	2003/03/17
		substrate board darrier poblish pb and traces and pads: and solder and inactive actives not a substrate board varirer poblish pb: and itraces and pads and solder and inactive and active:	USFĀT; US-PGPUB;	2003/03/17 12:48